



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

ADVANCE PRODUCT CHANGE NOTIFICATION

APCN: PCN162904

Date: August 02, 2016

Subject: Planned Qualification of New J-Devices Manufacturing Sites for MCU Products (updated revision of PCN161704)

To: General Inbox
NEWARK
Productchangenotices@newark.com

Change Type: Major

Description of Change:

Cypress announces its plans to qualify select MCU products at the J-Devices Hakodate and Fukuoka factories. This change is driven by the J-Devices announcement to relocate the Miyagi and Aizu production lines to other J-Devices facilities. New part numbers have been created for the parts that will be manufactured in Hakodate and Fukuoka factories. Please refer to attached 'Affected Parts List' file for the list of parts affected by this notice and the replacement parts.

Ball Grid Array (BGA)-packaged products that are currently assembled at the Miyagi factory and tested at the Aizu factory will be assembled and tested at the Hakodate factory. Lead frame (LF)-packaged products, including LQFPs, QFPs and SOPs, that are currently assembled at the Miyagi factory and tested at the Aizu factory will be assembled and tested at the Fukuoka factory. In concert with these production relocations, we anticipate that some of BGA-packaged products will also undergo a change in the Bill of Materials (BOM). Qualifications are planned to occur throughout 2016 with implementation taking place in 2017. Once the qualifications have been completed they will be announced through our normal PCN process.

The J-Devices Hakodate factory and the J-Devices Fukuoka factory have both been awarded international certifications in:

- ISO9001 - quality management systems,
- ISO14001 - environmental management systems, and
- ISO/TS16949 - automotive specific quality management systems

This is an advance notification and no immediate action is needed. Refer to the table below for the preliminary schedule of the activities including PCN issue dates and shipment start dates. Reliability reports and evaluation samples will be available by the PCN issue date. Note that the dates are subject to change. The preliminary timeline can be seen in the attached file.

Qualification	Current Site	New Site	Qualification/	First Shipments
---------------	--------------	----------	----------------	-----------------

			PCN / Samples	
BGA Assembly	J-Devices Miyagi	J-Devices Hakodate	Q4 2016	Q2 2017
BGA Test	J-Devices Aizu	J-Devices Hakodate	Q4 2016	Q2 2017
LF Assembly	J-Devices Miyagi	J-Devices Fukuoka	Q4 2016	Q2 2017
LF Test	J-Devices Aizu	J-Devices Fukuoka	Q4 2016	Q2 2017

Benefit of Change:

Qualification of these new sites will serve as a preventive action that will enable Cypress to continue meeting delivery commitments through qualified alternative sources.

Approximate Implementation Date:

Production at the J-Devices Hakodate and Fukuoka sites is expected to commence in early 2017.

Anticipated Impact:

No impact is expected in datasheet parameters, package composition or package pin-out.

Method of Identification:

Cypress announces the removal of the F-mark from IC markings on MCU products. The F-mark, representing the Fujitsu logo, has been used in the IC marking since the Fujitsu analog and MCU business was acquired by Spansion prior to the Cypress-Spansion merger. It has been three years since this business was separated from Fujitsu and the identifying mark is no longer needed. The marking layout will remain the same with the exception of deletion of the F-mark. Please refer to attached 'Affected Parts List' file for the parts that will go through F-mark removal.

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration